

To: _____**Change Notification: Photo IC coupler**

We appreciate your continued patronage of our semiconductor products.
Change is planned for the following product. Please refer to the following contents.
We would appreciate your understanding.

1. Affected product :

- Refer to the following page for the applicable product name.

2. Description of change : The following is changed for the applicable products.

No.	Main changes	Before change	After change
1	Additional production line	Existing line (One line)	Addition of new line (Total: Two lines)
2	Change in manufacturing process	Existing process	Existing process + High efficiency process
3	Stand-off dimension	0.95mm	0.95mm / 0.75mm
4	Root width of outer lead	0.60mm	0.60mm / 0.55mm

* Refer to the attachment (page 1 to 2) for the details.

3. Purpose of change

- 1) Parallel production with high efficiency production line.

4. Product characteristics

- 1) Manufacturing process partially changes (addition of high efficiency process), but there is no change in the internal structure and the quality of parts and materials. Therefore the initial characteristics and reliability level are same as existing product.

5. Schedule of change

- Products manufactured by the additional production line will be delivered from the production of January 2018.

6. Request

- Please inform us if you have any inconvenience on this change through our sales representatives by December 21, 2017.

Sincerely yours,



F. Hirano / Manager
Quality Planning Group
Quality Assurance Department
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(Drafted by T. Uchino)

Applicable product name (including the product of special specification)

6N135(F)	6N136(F)	6N137(F)	6N138(F)
6N139(F)	TLP250H(F)	TLP251(F)	TLP350H(F)
TLP351A(F)	TLP351H(F)	TLP352(F)	TLP358(F)
TLP358H(F)	TLP550(F)	TLP551(F)	TLP552(F)
TLP553(F)	TLP554(F)	TLP555(F)	TLP557(F)
TLP558(F)	TLP559(F)	TLP650(F)	TLP651(F)
TLP750(F)	TLP751(F)	TLP754(F)	TLP759(J,F)
TLP2200(F)	TLP2601(F)	TLP2955(F)	TLP2958(F)
TLP2962(F)	TLPN137(F)		